# CX20889 Low-Power USB Type C DSP CODEC AudioSmart™ Product Brief



# Integrated ARM<sup>®</sup> Cortex<sup>®</sup> M0+ MCU and Class-H Headphone Amplifier

#### **Product Overview**

The Conexant<sup>®</sup> AudioSmart™CX20889 is a single-chip solution for applications such as wired or wireless headsets, docking stations and voice command products. The CX20889 combines the benefits of a USB-C codec with the power of DSP. With an onboard 24-bit/96 kHz digital and analog I/O, microphone preamplifiers and a capless headphone amplifier, the CX20889 is a true single-chip solution for applications that demand high audio quality and lower power consumption.

Peripheral components expand the CX20889's utility, including:

- One I<sup>2</sup>C-bus master and one slave interface (or two I<sup>2</sup>C masters).
- Two I<sup>2</sup>S interfaces
- One Serial Peripheral Interface (SPI)
- Two multi-rate timers
- A self wake-up timer
- Four monitor ADCs
- Two PDM digital microphone interfaces
- S/PDIF input and output
- Up to 28 General Purpose Input/Output (GPIO) pins.

The CX20889 integrates a high-performance stereo ADC (98 dBA dynamic range) and DAC (105 dBA dynamic range).

Microphone performance is enhanced through programmable preamps paired with a dedicated bias supply to eliminate crosstalk. A ground-referenced output removes the need for capacitors on the headphone output, ensuring consistent performance with a wide variety of transducers. An integrated DC-DC converter supports internal power switches, dynamic voltage scaling, and frequency scaling mechanisms to reduce power consumption. It can also provide power for all peripheral devices connected to the board.

#### **Key Features**

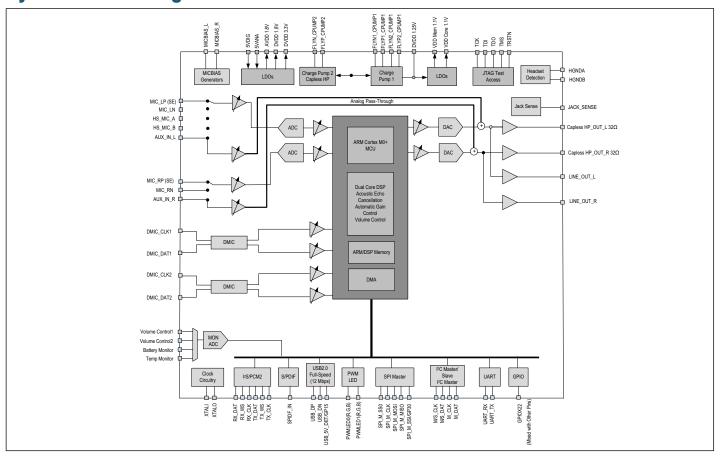
- ARM Cortex-M0+ controller, up to 50 MHz operation
- Conexant's dual-core, 32-bit hardware fixed point DSP, up to 100 MHz operation
- Floating point assist
- Up to 504 KB in SRAM
- Wake on Voice (WoV)
- Skype and USB 2.0 compliant full-speed device
- Ambient noise cancellation up to 30dB (depending on the headset design)
- Up to 3.5 kHz frequency band noise attenuation (depending on the headset design) with ANC
- Support of feed forward, hybrid ANC
- Adaptive ANC
- Two six-wire I<sup>2</sup>S/Pulse Code Modulation (PCM) devices
- S/PDIF input and output
- Two stereo PDM Digital Microphone Interfaces (DMICs)
- Two I<sup>2</sup>C masters, or one I<sup>2</sup>C master and one I<sup>2</sup>C slave One SPI connected to an external SPI flash memory with two Chip Selects (CSs).
- One UART supporting up to 3.125 Mbps data rate
- One watchdog timer
- Two tri-color, RGB (PWM) LED drivers
- One stereo ADC (98 dB dynamic range, A-weighted) and one stereo DAC (105 dB dynamic range, A-weighted)
- Standard sampling rates support 8 kHz to 96 kHz
- Built-in, four-conductor headset jack supports headphone/headset auto-detection, as well as auto switching between Apple-style and Nokia-style headsets.
- Four monitor 10-bit ADCs that support volume control, temperature sensor, and battery monitor.
- Up to 28 GPIOs
- Single wide range input power supply (2.70V–5.25V)
- Temperature range of –40°C to 85°C

# **Electrical Characteristics**

Parameter	Test Conditions	Minimum	Typical	Maximum	Unit
DAC Output Path (Lineout_R, Lineout_R) Line-Out Load R <sub>L</sub> =10kΩ					
Dynamic Range	-	-	105	-	dB
THD+N	–3 dBFS (0.707V <sub>rms</sub> )	-	<b>–</b> 79	-	dB
Crosstalk	10 kHz @ -20 dBFS	-	-92	-	dB
PSRR	100 mV <sub>p-p</sub> , 1 kHz, Any Supply 100 mV <sub>p-p</sub> , 10 kHz, Any Supply	-	-	-	dB
DAC Output Path (HP_L, HP_R) Hea	dphone Load R <sub>L</sub> =32 Ω				
Dynamic Range	-	-	104	-	dB
THD+N	$-3 \text{ dBFS } (0.707 \text{V}_{rms}) \text{ Pout} = 15.6 \text{ mW}$	-	<b>–</b> 77	-	dB
Crosstalk	10 kHz @ -20 dBFS	-	-83	-	dB
PSRR 100 mV <sub>p-p</sub> , 1 kHz, Any Supply 100 mV <sub>p-p</sub> , 10 kHz, Any Supply		-	-	-	dB
Headphone Output Driver (HP_L, HF	P_R)				
Minimum Output Load Resistance	-	TBD	-	-	Ω
Maximum Output Load Capacitance -		-	-	400	pF

Parameter	Test Condition	Minimum	Typical	Maximum	Units	
Maximum Full Scale	Single-ended Input	-	-	0.5	Vrms	
Input				<b>–</b> 6	dBv	
	Differential Input			1	Vrms	
		-	-	0	dBv	
Input Resistance	Line-In (Single-ended) –6dB		8K			
	Line-In (Single-ended) 0dB		16K		0	
	Mic-In (Single-ended)	-	500K	-	Ω	
	Mic-In (Differential)		500K			
Programmable Gain	Line-In (Single-ended)	<b>-</b> 6	-	0		
	Line-In Gain Step	-	6	-	٩D	
	Mic-In (Single-ended and Differential)	6	-	30	dB	
	Mic-In Gain Steps	-	1	-		
Dynamic Range	Differential Mic-In (6dB PGA Gain)	-	98.1	-	dB	
THD+N	Differential Mic-In (6dB PGA Gain) -3 dBFS	-	-86	-	dB	
Channel Separation	Differential Mic-In	-	<b>–</b> 87	-	dB	
Common Mode Rejection	-20 dBV Input of 217 Hz PGA in Differential Mode; 6 dB Gain	-	-85	-	dB	

# **System Block Diagram**



#### **Benefits**

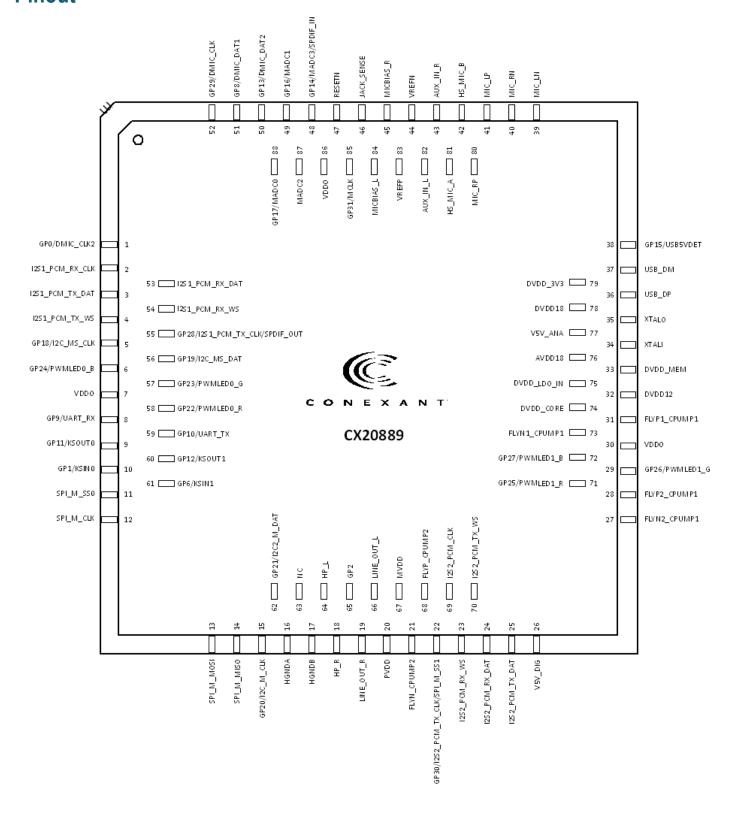
- Brings USB-C technology to mobile/portable devices that require low power consumption.
- Adds extensive DSP capabilities for easy and powerful tuning of audio products.
- Ideal for wired or wireless headsets, docking stations, voice recognition, and many other applications.

#### **Test Conditions**

- V5V\_DIG = V5V\_ANA = 5V
- DVDD12 = 1.2V
- AVDD18 = DVDD18 = PVDD = 1.8V
- MVDD=-1.7V, AGND=DGND=0V
- T<sub>A</sub> = 25°C

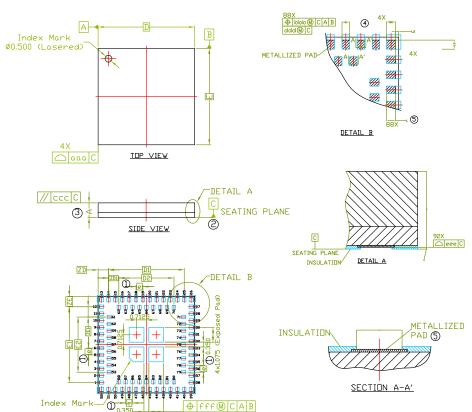
- fin = 997 Hz
- fs = 48 kHz
- Gain setting = 0 dB
- 24-bit audio data

### **Pinout**



# CX20889 Low-Power USB Type C DSP CODEC | AudioSmart™ Product Brief

# **Package Drawing**



DIMENSIONAL REFERENCES				
Symbol	Dimension in mm			
Symbol	Min	Nom	Max	
A	0.83	0.9	0.97	
A1	-	-	0.05	
A2	-	-	0.92	
D	7.00 BSC			
E	7.00 BSC			
D1	5.50 BSC			
E1	5.50 BSC			
D2	4.00 BSC			
E2	4.00 BSC			
е	0.50 BSC			
b	0.20	0.25	0.30	
L	0.25	0.30	0.35	
b1	0.25	0.30	0.35	
L1	0.25	0.30	0.35	
L2	0.10 BSC			

Symbol	Dimension in mm		
Symbol	Min	Nom	Max
ZD	0.75 BSC		
ZE	0.75 BSC		
ZD1	0	.75 BSC	:
ZE1	C	.75 BSC	;

#### DIMENSIONAL REFERENCES 0.10 0.10 0.20 0.08 0.08 fff 0.10

- BATUM "C' IS THE MOUNTING SUMMANGE, ALL.

  SIM CONTACT.

  DIMENSION "AN INCLUDES PACKAGE WARPAGE.

  DIMENSION "AN APPLIES TO METALLIZED THEMPIAL AND IS MEASURE

  DIMENSION "AN APPLIES TO METALLIZED THEMPIAL.

  METALLIZED PADS ARE CO PAD WITH IT'S EXPOSED SURFACE

  PLATED WITH NE ABL.

  ACKAGE DIMENSIONS TAKE REFERENCE FROM JEDEC MO-208 REV.C.

## **Ordering Information**

BOTTOM VIEW

Ordering Part Number	Part Number	Description	Package
DSAC-L889-10CH	CX20889-10Z	Low-Power USB Type C DSP CODEC.	7 x 7 mm 88-pin VLGA

#### www.conexant.com

Headquarters: 1901 Main Street, Suite 300 Irvine, CA 92614

General Information: U.S. and Canada: 888-855-4562 | International: +1 949-483-3000

044-889PBR04

